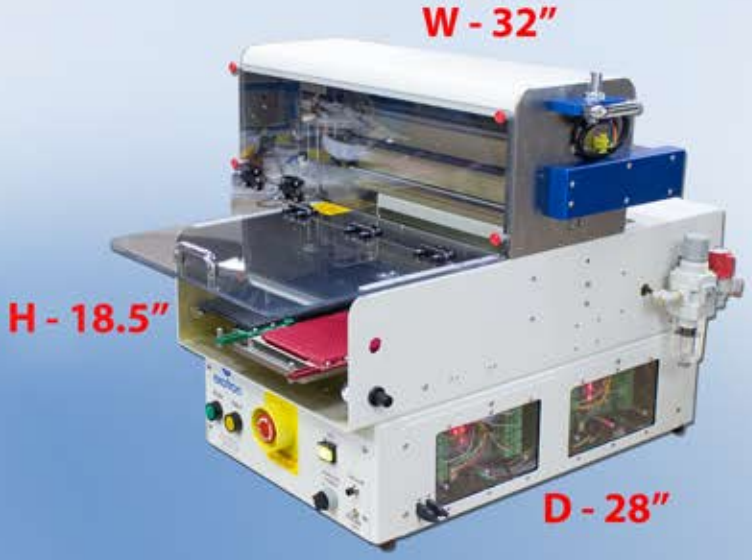
exatron MODEL 802 THERMAL

TABLE TOP DUAL TEMP THERMAL TEST HANDLER

- Hot and cold thermal test.
- Features Exatron's Wide Range Thermal Head (WRTH)

  (-75°C) -55°C to +155°C (+175°C) working range.
- Handles all SMD and leaded device types from 1.6 x 1.6mm to 60 x 60mm.
- Near zero mechanical adjustments or changeover kits.
- Bottom-side calibration camera ensures precise alignment. (Option)
- Designed and manufactured in the USA.

Wide range thermal testing in a powerful small package



exatron
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exatron MODEL 802 TABLE TOP

SPECIFICATIONS, FEATURES, AND OPTIONS

Specifications:

Size:	81cm W x 71cm D x 47cm H (32" W x 28" D x 18.5" H) (excludes light pole) (With 32" gantry.)
Weight:	Under 45Kg (under 100 lbs.)
Power:	120 VAC 60 Hz or 220 VAC 50/60 Hz
Air:	5.5 bar (80 PSI) - 2 CFM clean, dry air
Operational Temperature:	13-32°C (55-90°F)
Humidity:	30-45% RH non-condensing (required for cold test)

Positioning System:

X-Y Drive System:	Servo motor-driven lead screws
X-Y Axis Resolution:	0.1mm (0.003")
X-Y Axis Max. Velocity:	122cm/s (48"/s) (High speed gantry optional)
Z Plunger:	Servo motor-driven lead screw
Z Axis Resolution:	+/- 0.1mm (0.003")
Z Axis Repeatability:	+/- 0.1mm (0.003")
Theta Drive System (optional):	Precision stepper motor
Theta Axis Resolution:	0.1°
Theta Axis Repeatability:	+/- 0.1mm (0.003")

802 Table Top Features:

Device types: BGA, CSP, DIP, Flat Pack, LCC, LGA, MSOP, PCB, PGA, PLCC, QFP, SIMM, SIP, SIMM, SODIMM, SOIC, SSOIC, TSSOP, and custom.

Test site: Single site standard. Dual sites available.

Test sockets: Supports nearly all OEM test sockets; Exatron custom-built spring probe sockets; and Exatron Particle Interconnect (PI) RF & CSP

DUT board: 8" clearance under board; up to 12" x 12" square with centered socket; many mounting options.

Contact Force: 0-20 lbs standard, software controlled.

Test Interface: RS-232, Ethernet

Jam rate: 1/5000 when using Exatron test sockets.

Tray: Fits all formats of JEDEC tray, 2" and 4" waffle packs.

Binning: Up to 8 sorts standard, output tray sort mapping; drop to bucket standard.

Double part protection:

Standard built-in vacuum sensor checks for empty socket at start of job and before each pick and place.

Precisor: Mechanical precisor ready; built-in controls for many precisor options.

Changeover: Nearly kit-less - change pick up tip (if needed) change test socket, load new trays, load previously set up JOB file. All mechanical changeover adjustments software-controlled.

Options:

VISION UPGRADES: (May require longer gantry)

- Top-side OCR camera
- Bottom-side 2D and 3D lead inspection (requires table option)

MARKING UPGRADES:

- In-tray laser marking

MEDIA UPGRADES: (May require longer gantry)

- Detaper input
- Exatron-built tape and reel output
- Small volume tube to tube
- Bucket output

TEST INTERFACE OPTIONS:

- TTL/opto isolated
- GPIB

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